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Haupt
2/29/2002

BY THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Jiang et al.

Serial No.: 09/944,015

Filed: August 30, 2001

For: PLASTIC LEAD FRAMES FOR
SEMICONDUCTOR DEVICES, PACKAGES
INCLUDING SAME, AND METHODS OF
FABRICATION

Examiner: Unknown

Group Art Unit: 2814

Attorney Docket No.: 3086.7US (96-1006.7)

CERTIFICATE OF MAILING

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PRELIMINARY AMENDMENT

Box Non-Fee Amendment
Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to examination of the above-referenced patent application on the merits, entry of the amendments as set forth herein is respectfully solicited.